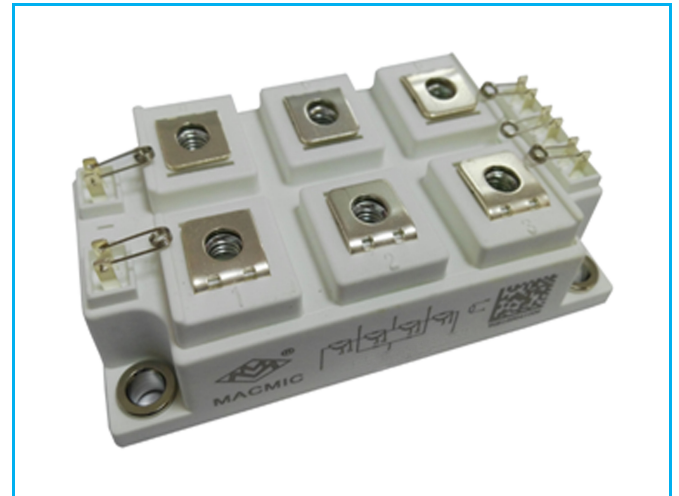


## PRODUCT FEATURES

- IGBT CHIP(Trench+Field Stop technology)
- Low saturation voltage and positive temperature coefficient
- Low switching losses and short tail current
- Free wheeling diodes with fast and soft reverse recovery
- Temperature sense included

## APPLICATIONS

- 3-Level-Applications
- Solar Applications
- UPS Systems



### IGBT(T1、 T2、 T3、 T4)

ABSOLUTE MAXIMUM RATINGS( $T_C=25^{\circ}\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{CES}$	Collector Emitter Voltage	$T_J=25^{\circ}\text{C}$	650	V
$V_{GES}$	Gate Emitter Voltage		$\pm 20$	
$I_C$	DC Collector Current	$T_C=25^{\circ}\text{C}, T_{Jmax}=175^{\circ}\text{C}$	350	A
		$T_C=60^{\circ}\text{C}, T_{Jmax}=175^{\circ}\text{C}$	300	
$I_{CM}$	Repetitive Peak Collector Current	$t_p=1\text{ms}$	600	
$P_{tot}$	Power Dissipation Per IGBT	$T_C=25^{\circ}\text{C}, T_{Jmax}=175^{\circ}\text{C}$	882	W

### Diode(D1、 D2、 D3、 D4、 D5、 D6)

ABSOLUTE MAXIMUM RATINGS ( $T_C=25^{\circ}\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{RRM}$	Repetitive Reverse Voltage	$T_J=25^{\circ}\text{C}$	650	V
$I_{F(AV)}$	Average Forward Current		300	A
$I_{FRM}$	Repetitive Peak Forward Current	$t_p=1\text{ms}$	600	
$I^2t$		$T_J=125^{\circ}\text{C}, t=10\text{ms}, V_R=0\text{V}$	7200	$\text{A}^2\text{S}$

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# MMG300B065PD6TC

IGBT(T1、T2、T3、T4)

ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}, I_C=4.8\text{mA}$	5.0	6.0	6.5	V
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$I_C=300\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$		1.55	2.0	
		$I_C=300\text{A}, V_{GE}=15\text{V}, T_J=125^\circ\text{C}$		1.75		
		$I_C=300\text{A}, V_{GE}=15\text{V}, T_J=150^\circ\text{C}$		1.8		
$I_{CES}$	Collector Leakage Current	$V_{CE}=650\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$			1	mA
		$V_{CE}=650\text{V}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$			5	
$I_{GES}$	Gate Leakage Current	$V_{CE}=0\text{V}, V_{GE}=\pm 20\text{V}, T_J=25^\circ\text{C}$	-400		400	nA
$R_{gint}$	Integrated Gate Resistor			1		$\Omega$
$Q_g$	Gate Charge	$V_{CE}=300\text{V}, I_C=300\text{A}, V_{GE}=15\text{V}$		1.4		$\mu\text{C}$
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		19.4		nF
$C_{res}$	Reverse Transfer Capacitance				800	
$t_{d(on)}$	Turn on Delay Time	$V_{CC}=300\text{V}, I_C=300\text{A}$ $R_G=1.5\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		70	ns
			$T_J=150^\circ\text{C}$		80	ns
$t_r$	Rise Time	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		65	ns
			$T_J=150^\circ\text{C}$		70	ns
$t_{d(off)}$	Turn off Delay Time	$V_{CC}=300\text{V}, I_C=300\text{A}$ $R_G=1.5\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		370	ns
			$T_J=150^\circ\text{C}$		400	ns
$t_f$	Fall Time	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		60	ns
			$T_J=150^\circ\text{C}$		65	ns
$E_{on}$	Turn on Energy	$V_{CC}=300\text{V}, I_C=300\text{A}$ $R_G=1.5\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		4.1	mJ
			$T_J=125^\circ\text{C}$		5.2	mJ
			$T_J=150^\circ\text{C}$		6.1	mJ
$E_{off}$	Turn off Energy	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		9.5	mJ
			$T_J=125^\circ\text{C}$		11.2	mJ
			$T_J=150^\circ\text{C}$		12	mJ
$I_{SC}$	Short Circuit Current	$tpsc \leq 6\mu\text{S}, V_{GE}=15\text{V}$ $T_J=125^\circ\text{C}, V_{CC}=360\text{V}$		1400		A
$R_{thJC}$	Junction to Case Thermal Resistance (Per IGBT)				0.17	K/W

Diode(D1、D2、D3、D4、D5、D6)

ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_F$	Forward Voltage	$I_F=300\text{A}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$		1.7	2.1	V
		$I_F=300\text{A}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$		1.55		
		$I_F=300\text{A}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$		1.45		
$t_{rr}$	Reverse Recovery Time	$I_F=300\text{A}, V_R=300\text{V}$ $dI_F/dt=-4000\text{A}/\mu\text{s}$ $T_J=150^\circ\text{C}$		160		ns
$I_{RRM}$	Max. Reverse Recovery Current			195		A
$Q_{RR}$	Reverse Recovery Charge			17		$\mu\text{C}$
$E_{rec}$	Reverse Recovery Energy			7.8		mJ
$R_{thJCD}$	Junction to Case Thermal Resistance (Per Diode)				0.3	K/W

# MMG300B065PD6TC

## NTC CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions	Min.	Typ.	Max.	Unit
$R_{25}$	Resistance $T_C=25^\circ\text{C}$		5		K $\Omega$
$B_{25/50}$	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298.15 \text{ K}))]$		3375		K

## MODULE CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions	Values	Unit	
$T_{Jmax}$	Max. Junction Temperature	175	°C	
$T_{Jop}$	Operating Temperature	-40~150		
$T_{stg}$	Storage Temperature	-40~125		
$V_{isol}$	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), t=1minute	3000	V
CTI	Comparative Tracking Index		> 200	
Torque	to heatsink	Recommended (M6)	3~5	Nm
	to terminal	Recommended (M6)	3~5	Nm
Weight			300	g

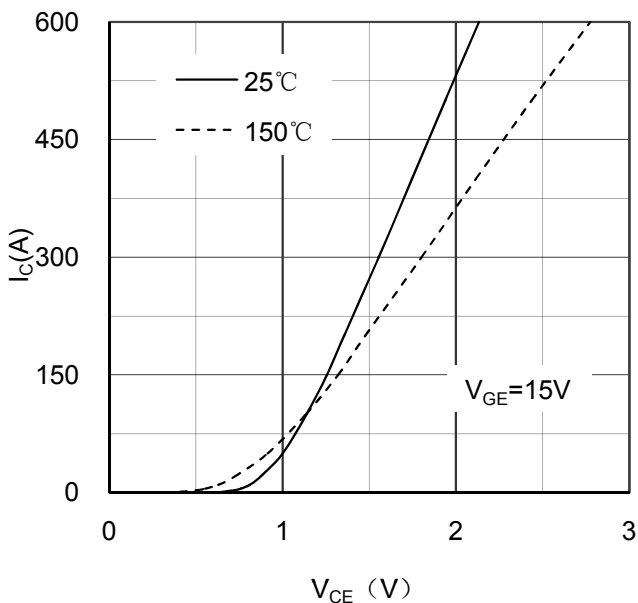


Figure 1. Typical Output Characteristics IGBT

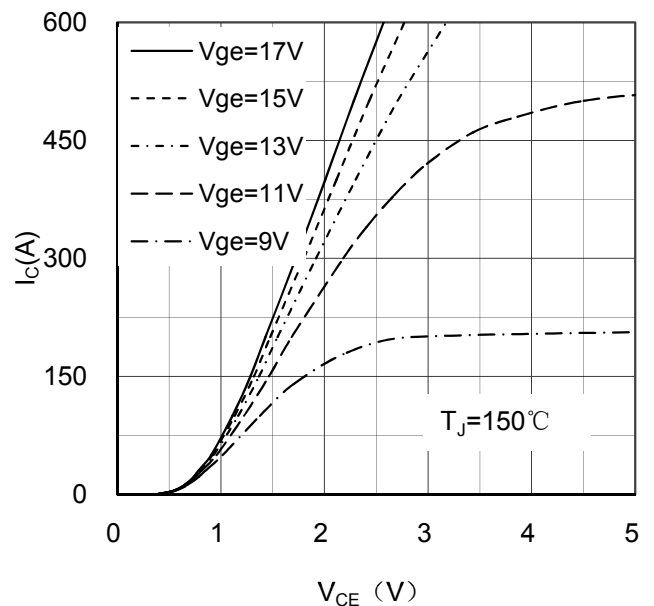


Figure 2. Typical Output Characteristics IGBT

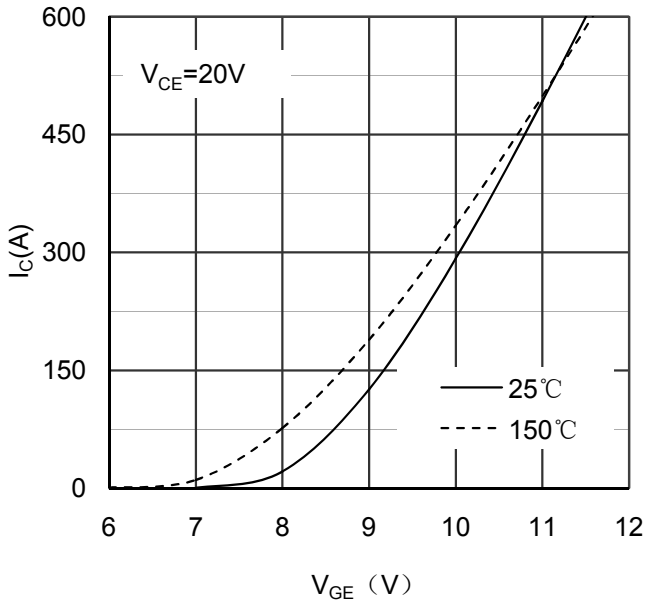


Figure 3. Typical Transfer characteristics IGBT

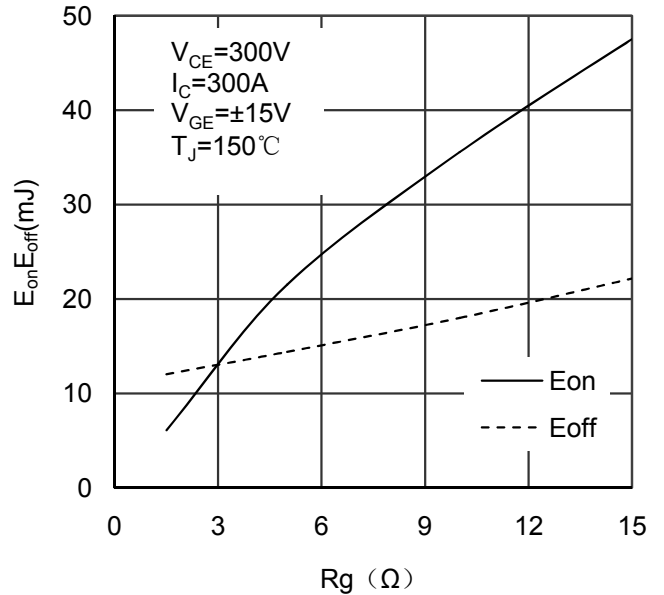


Figure 4. Switching Energy vs Gate Resistor IGBT

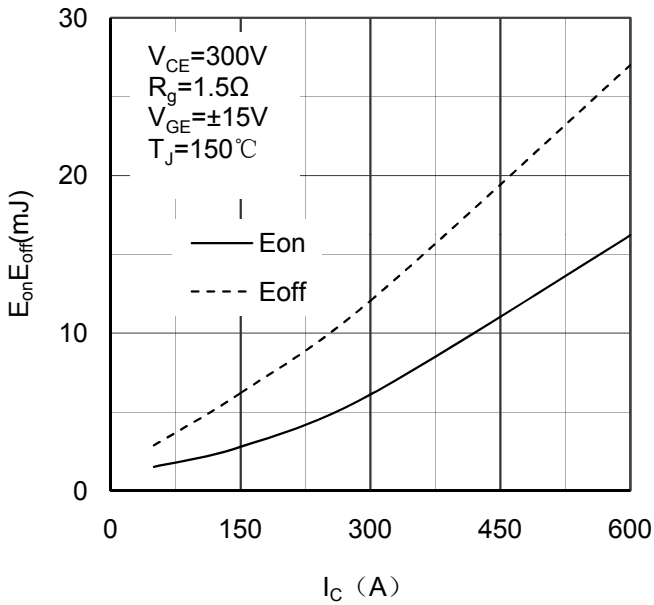


Figure 5. Switching Energy vs Collector Current IGBT

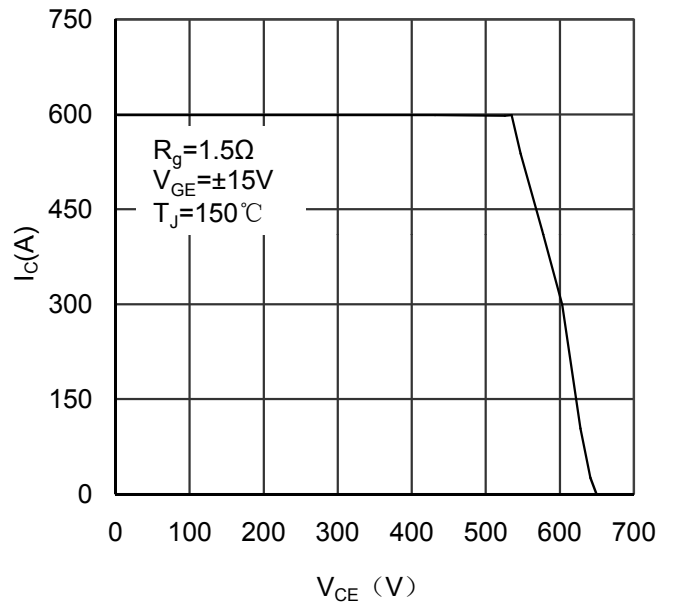


Figure 6. Reverse Biased Safe Operating Area IGBT

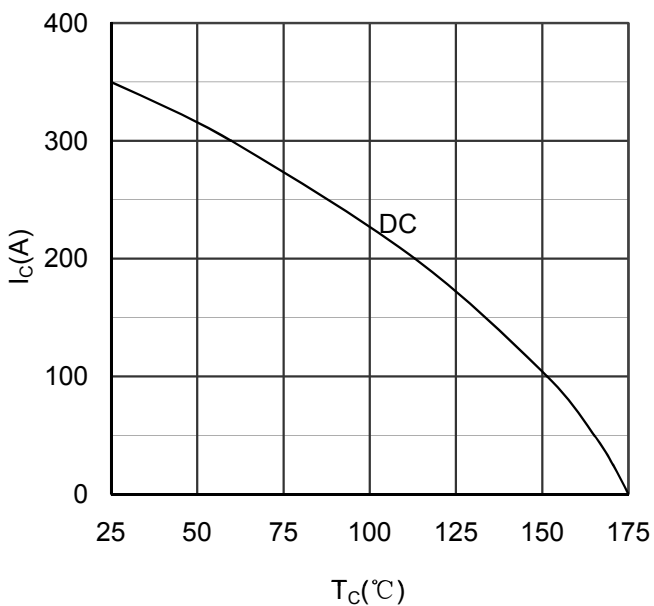


Figure 7. Collector Current vs Case temperature IGBT

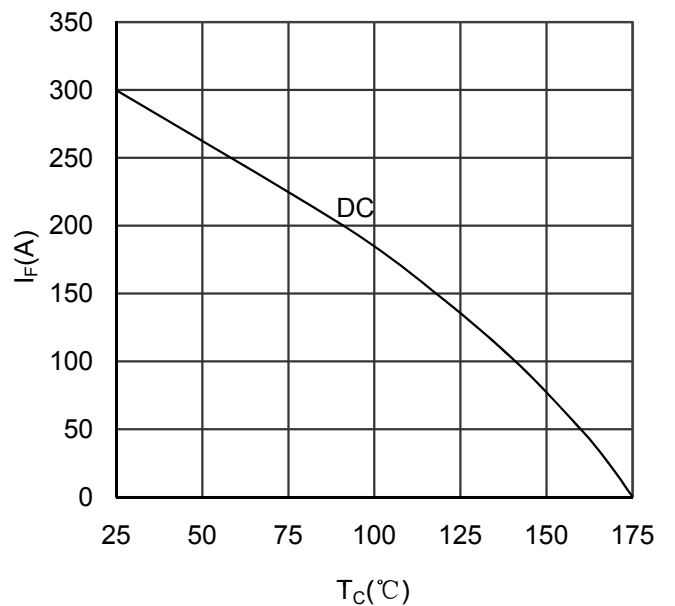


Figure 8. Forward current vs Case temperature Diode

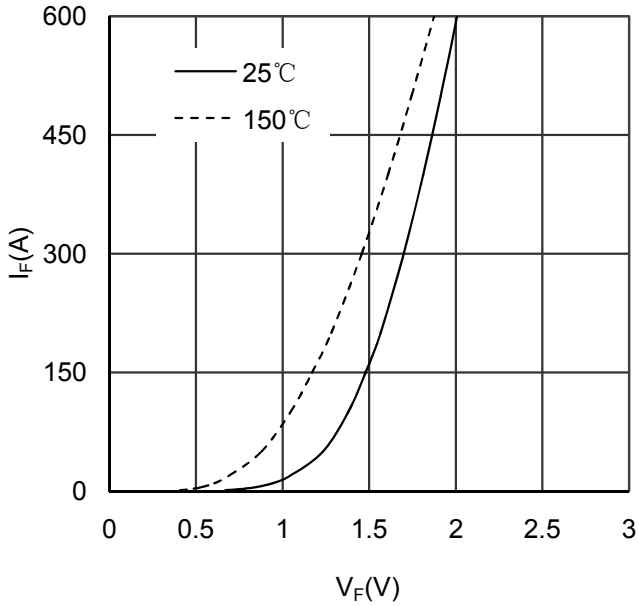


Figure 9. Diode Forward Characteristics Diode

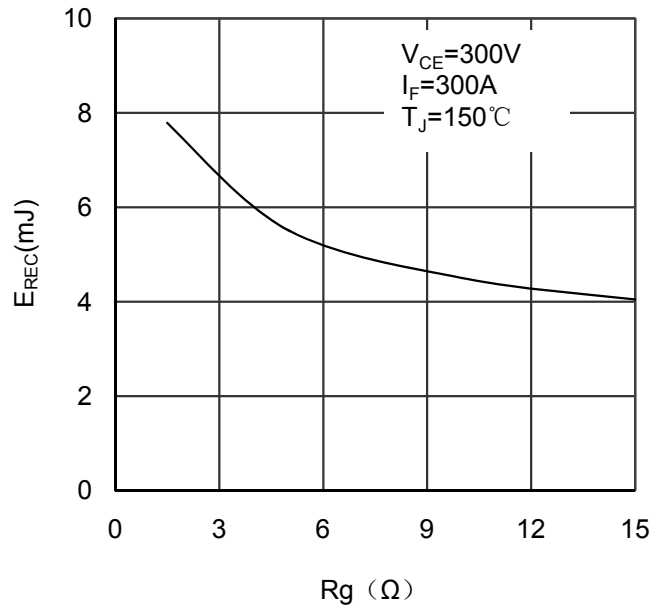


Figure 10. Switching Energy vs Gate Resistor Diode

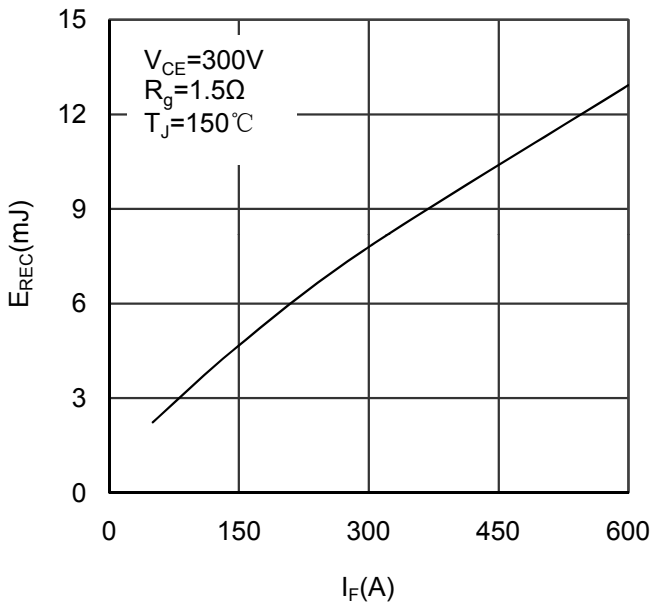


Figure 11. Switching Energy vs Forward Current Diode

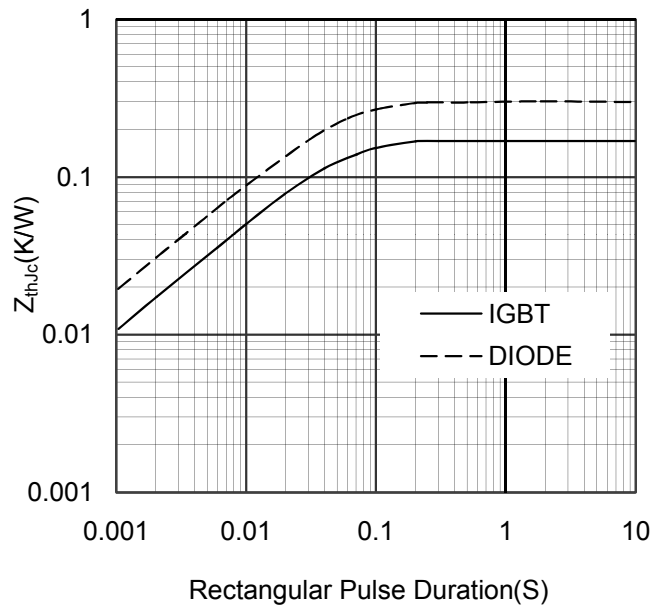


Figure 12. Transient Thermal Impedance of Diode and IGBT

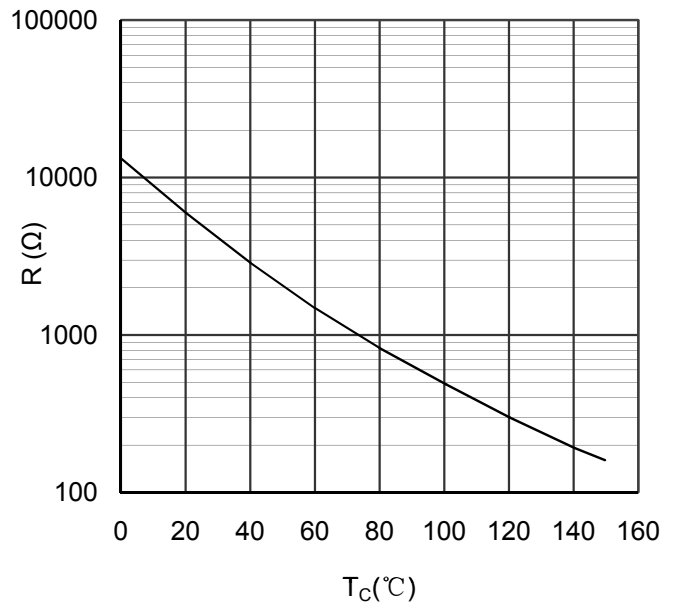


Figure 13. NTC Characteristics

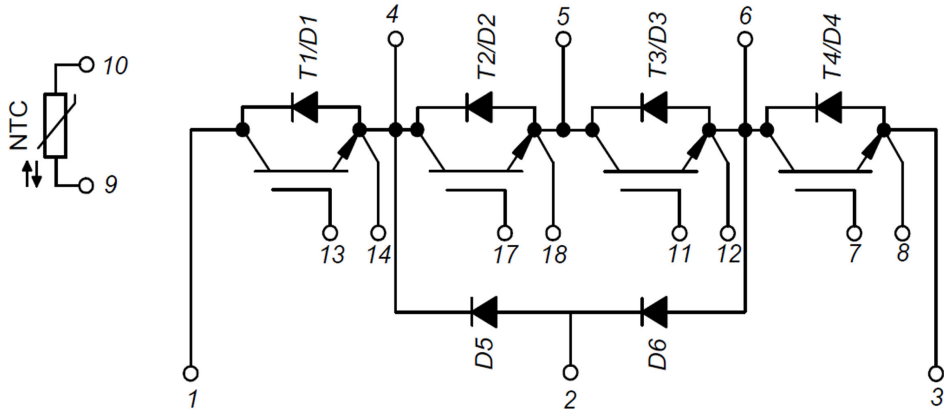
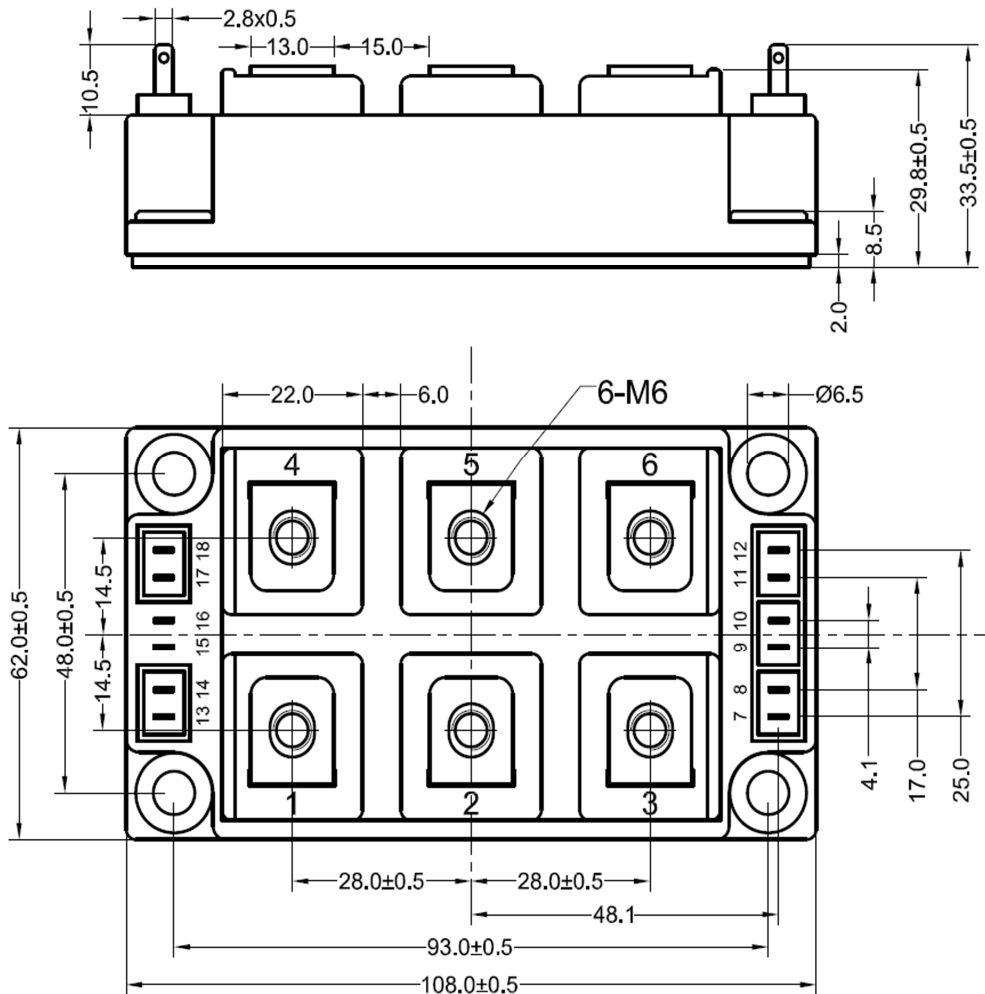


Figure 14. Circuit Diagram



Dimensions in (mm)

Figure 15. Package Outline